

# 期末复习

2024. 1. 8

# 考试题型

- 名词解释:  $6 \times 2 \text{分} = 12 \text{分}$  (IC CMOS PMOS NMOS ...)
- 选择:  $11 \times 2 \text{分} = 22 \text{分}$
- 解答题:  $5 \times X \text{分} = 66 \text{分}$  (Analog 2, Digital 2, Layout 1)
  - 模拟小信号模型与计算
  - 看版图, 从版图画出 Schematic
  - 从布尔函数到数字逻辑门
  - 多输入逻辑门延时计算

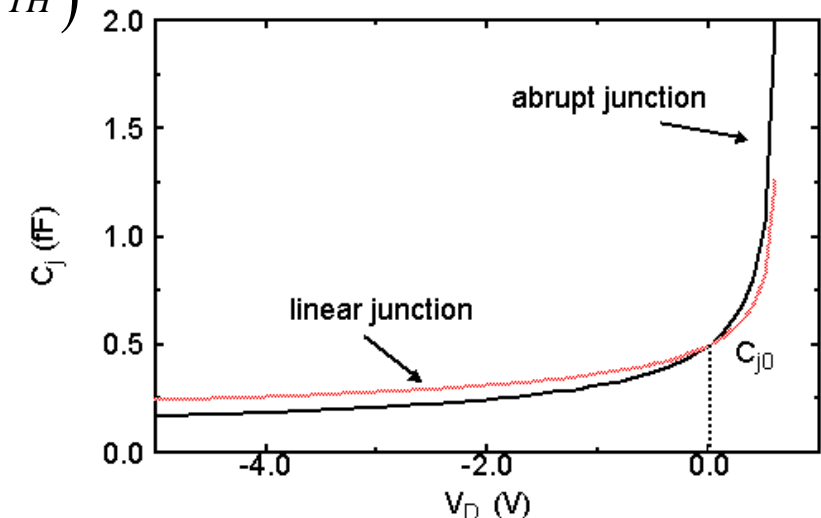
# 主要内容 (1)

- Technology scaling down (digital driven) with Moore's Law  
But in recent decade more SoC, SiP and Chiplets
- Analog & Digital Design Flow (Transistor level vs. Behavior-RTL)
- Analog vs. Digital with technology scaling down
- I/V curve and operation region of MOSFET

$$I_D = \mu_n C_{OX} \frac{W}{L} \left[ (V_{GS} - V_{TH}) V_{DS} - \frac{1}{2} V_{DS}^2 \right] \quad I_D = \frac{1}{2} \mu_n C_{OX} \frac{W}{L} (V_{GS} - V_{TH})^2$$

- Diode and its capacitance

$$C_j = \frac{C_{j0}}{(1 - V_D / \phi_0)^m}$$



# 主要内容 (2)

- Body Effect & Channel Length Modulation & **Weak inversion**

$$V_{TH} = V_{TH0} + \gamma \left( \sqrt{|2\Phi_F + V_{SB}|} - \sqrt{|2\Phi_F|} \right)$$

$$I_D \approx \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2 (1 + \lambda V_{DS})$$

$$I_D = I_0 \exp \frac{V_{GS}}{\zeta V_T}$$

- Small Signal Model

管子是一个压控电流源，主要由Vgs控制，受到Vds的影响

# Single-Page MOSFET Model

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$$I_{DS} = K'_n \frac{W}{L} (V_{GS} - V_T)^2 \quad V_{GS} - V_T \approx 0.2 \text{ V} \quad \begin{matrix} K'_n \approx 100 \mu\text{A/V}^2 \\ K'_p \approx 40 \mu\text{A/V}^2 \end{matrix}$$

$$K'_n = \frac{1}{2} \mu_n C_{ox}$$

$$g_m = 2K'_n \frac{W}{L} (V_{GS} - V_T) = 2 \sqrt{K'_n \frac{W}{L} I_{DS}} = \frac{2 I_{DS}}{V_{GS} - V_T}$$

$$r_{DS} = r_o = \frac{V_E L}{I_{DS}}$$

$$V_{En} \approx 5 \text{ V}/\mu\text{mL} \quad V_{Ep} \approx 8 \text{ V}/\mu\text{mL} \\ v_{sat} = 10^7 \text{ cm/s}$$

$$r_o = \frac{1}{I_D \lambda}$$

$$f_T = \frac{1}{2\pi} \frac{3}{2n} \frac{\mu}{L^2} (V_{GS} - V_T) \quad \text{or now} \approx \frac{v_{sat}}{2\pi L}$$

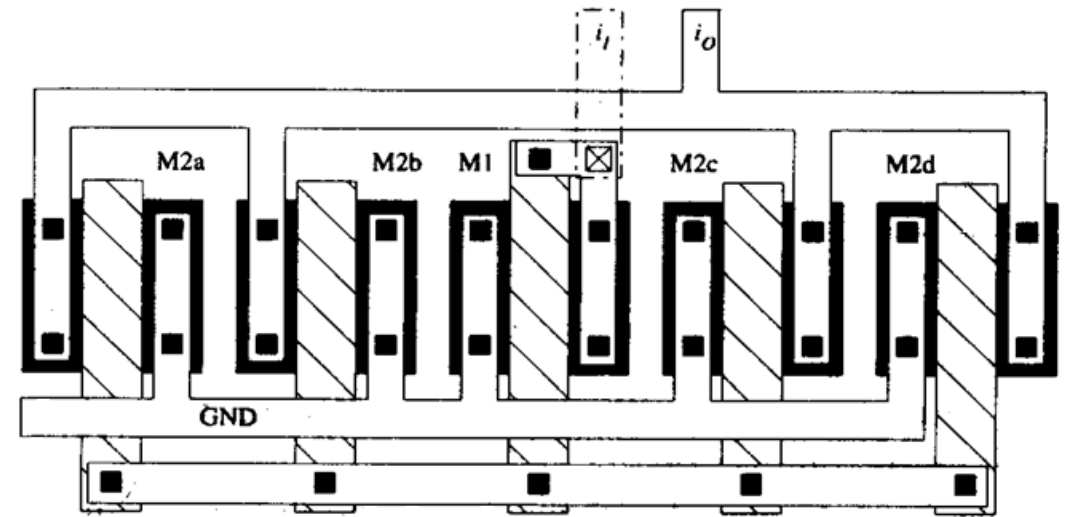
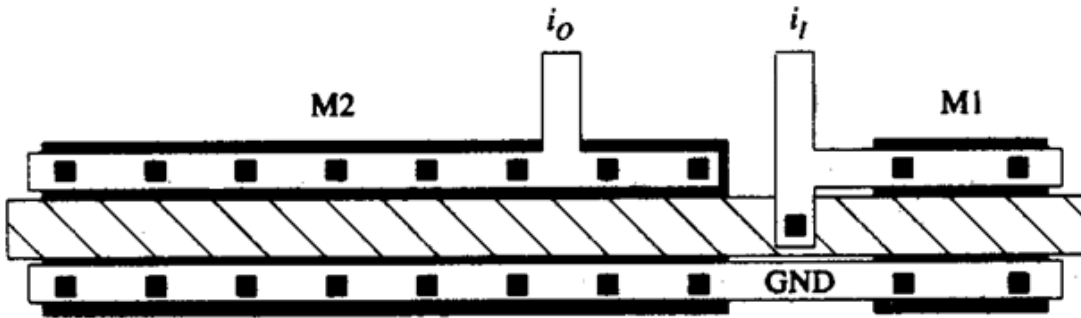
$$f_T = \frac{g_m}{2\pi C_{GS}}$$

# 主要内容 (3)

- PVT variation of parameters: (+)  $R$ ,  $g_m$ , speed... (-)  $V_{th}$ ,  $V_{be}$ ...
- Process Steps:
  1. Wafer preparation
  2. **Lithography** (defines the geometry )
  3. Oxidation,
  4. Diffusion, Ion immolations, Deposition
  5. Etching **(2-5)不断循环**
  6. Planarization
- DRC (minimum distance, matching etc.) LVS (Layout vs Schematic)

# 主要内容 (4)

- Layout: from Layout to schematic
- Matching: **identical cells** are good for matching  
(用多个一样的-电流镜)



- Two dimensional matching (交差摆放-差分对)

# 主要内容 (5)

$$r_{ON} = \frac{1}{\partial i_D / \partial v_{DS}} \bigg|_Q$$

- Switch (charge feedthrough) in linear:  $= \frac{L}{K'W(V_{GS} - V_{TH} - V_{DS})}$
- Active resistor (diode connected transistor) in saturation (1/gm)
- Current mirror: 一个由二极管连接的管子控制栅极的管子:  $r_{ds}$
- Cascode current mirror: 输出阻抗被提升至  $r_{ds}$  的  $(gm \cdot r_{ds})$  倍  
 $gm \cdot r_{ds}$  为上面管子的本征增益, PMOS则相反, 为下面管子
- 一些电压关系计算, 压低最小输出电压



# 主要内容 (6)

- **Common-Source Stage**

- Inverse Gain -> I-V curve (why  $R_D < r_o$  of transistor)
- 增益等于输入管 $g_m$ \*输出节点的阻抗 (上下并联)

- **Source Follower**

$$G_m = g_m / (1 + g_m R_S)$$

With high output resistance  
Similar to Cascode

- **Common-Gate Stage**

Current input with  $(1/g_m)$  ->  $I_{out} = I_{in}$

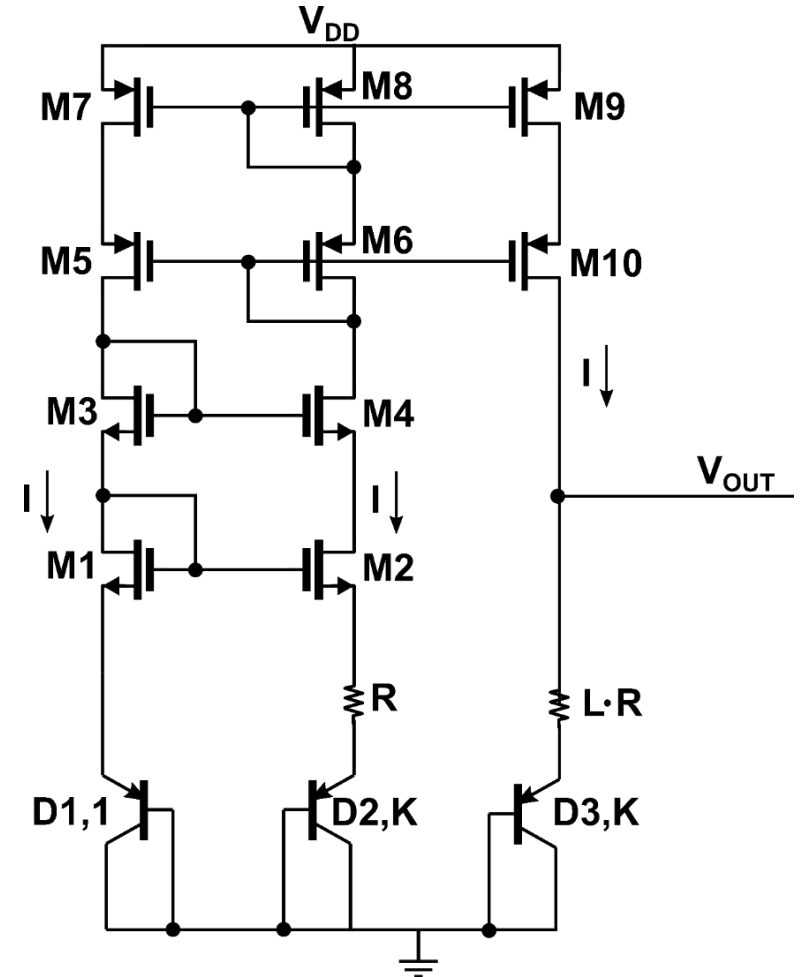
With low input resistance:  $1/g_m$

# 主要内容 (7)

- Bandgap reference (ZTC = PTAT+CTAT)

$$V_{REF} = V_{BE} + KV_t$$

$$\begin{aligned} V_{ref} &= V_{EB3} + I \times LR \\ &= V_{EB3} + \frac{V_t \ln K}{R} \times LR \\ &= V_{EB3} + LV_t \ln K \end{aligned}$$



# 主要内容 (8)

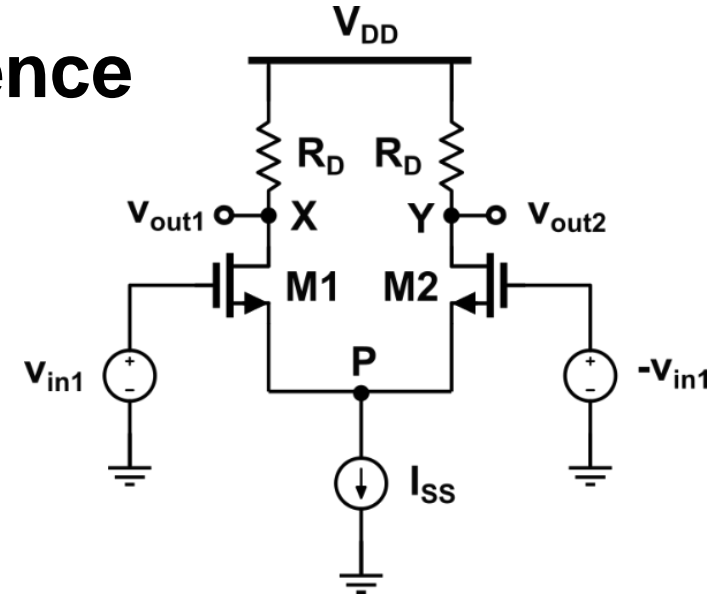
- A differential signal is better in PSRR/Interference
- Virtual ground at node P with fixed  $I_{SS}$

- $V_{in,cm}$  Range:  $V_{GS1} + (V_{GS3} - V_{TH3}) \leq V_{in,CM} \leq V_{DD} - R_D \frac{I_{SS}}{2} + V_{TH3}$

- DM small signal gain:  $-G_m * R_{out}$

增益等于输入管 $g_m$ \*输出节点的阻抗 (上下并联)

- CM small signal gain:  $(g_m / (1 + g_m r_{ss})) * R_{out}$
- OTA with five transistors

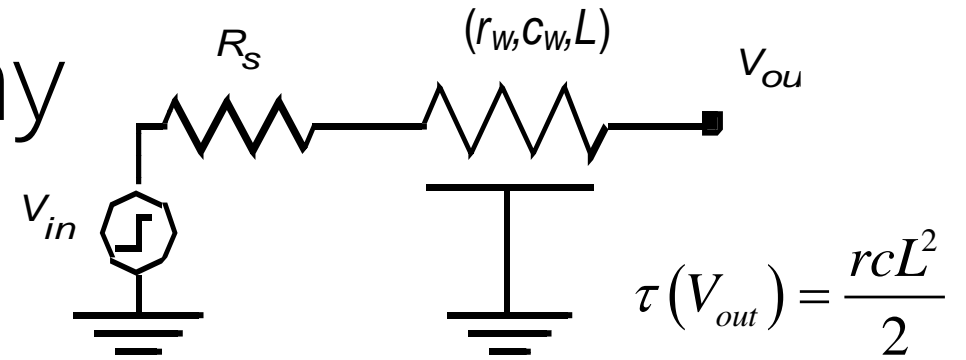


# 主要内容 (9) 运算放大器一般性了解即可

- Ideal Opamp
- DC gain and dominant pole of single stage, telescopic and folded-cascade amplifier
- DC gain and two poles of two stage amplifier, after miller compensation
- Input and output range  
(every transistor in saturation)
- Speed and Slew rate  
(small signal and large signal behavior)

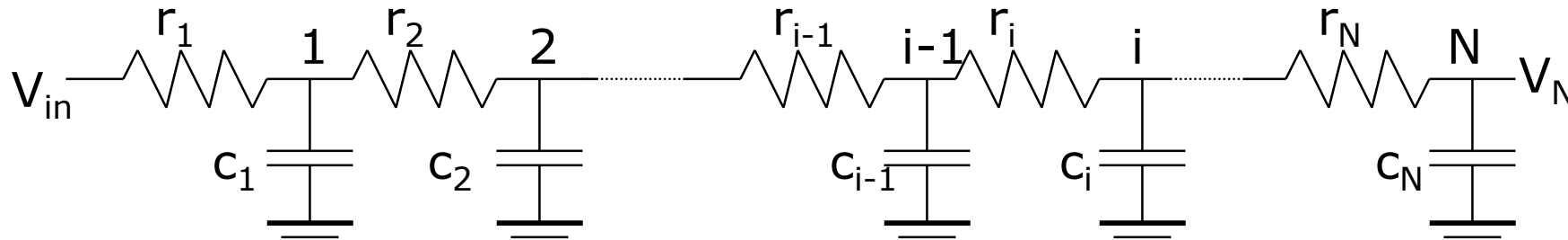
# 主要内容 (10) Elmore delay

- Wire parasitics
  - Capacitance, Resistance, Inductance
- Wire models (lumped, distributed)



$$\tau_D = R_s C_w + \frac{R_w C_w}{2} = R_s C_w + 0.5 r_w c_w L^2$$

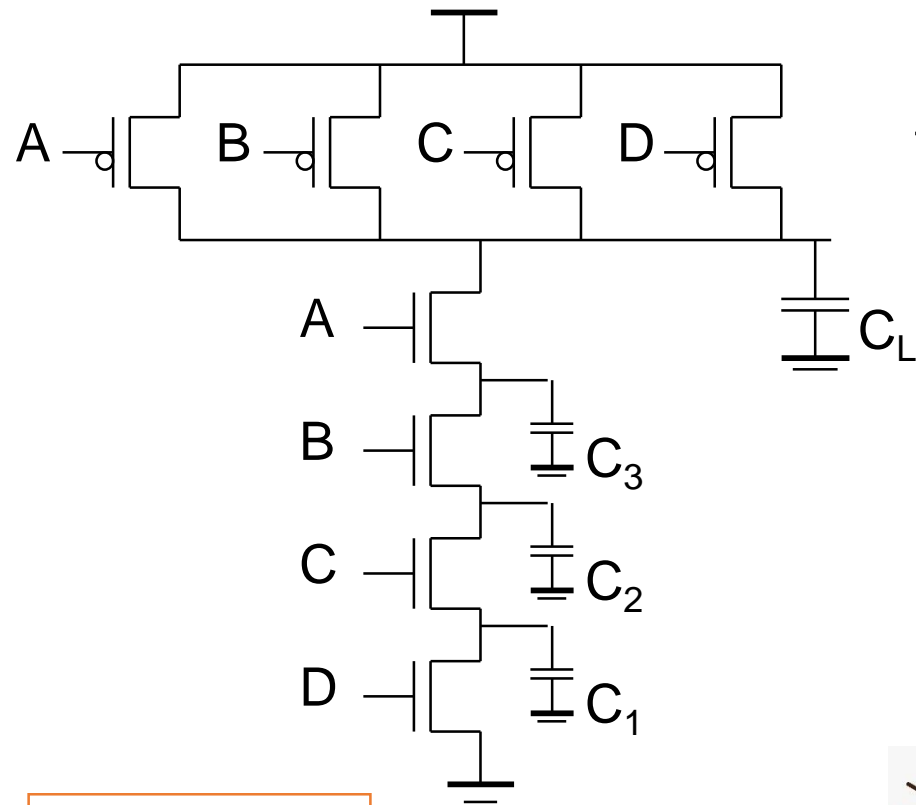
$$t_p = 0.69 R_s C_w + 0.38 R_w C_w$$



$$\tau_{Di} = C_1 r_1 + C_2 (r_1 + r_2) + \dots + C_i (r_1 + r_2 + \dots + r_i)$$

$$\tau_{Di} = C_1 r_{eq} + 2C_2 r_{eq} + 3C_3 r_{eq} + \dots + iC_i r_{eq}$$

# 主要内容 (10) Elmore delay of gates



Distributed RC model (Elmore delay)

$$t_{pHL} = 0.69 [R_1 C_1 + (R_1 + R_2) C_2 + (R_1 + R_2 + R_3) C_3 + (R_1 + R_2 + R_3 + R_4) C_L]$$

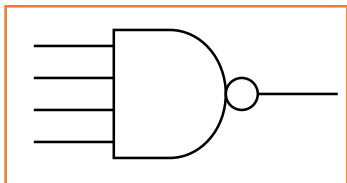
NMOS: same size  $R_{eqn}$

$$t_{pHL} = 0.69 R_{eqn} (C_1 + 2C_2 + 3C_3 + 4C_L)$$

**the worst-case**

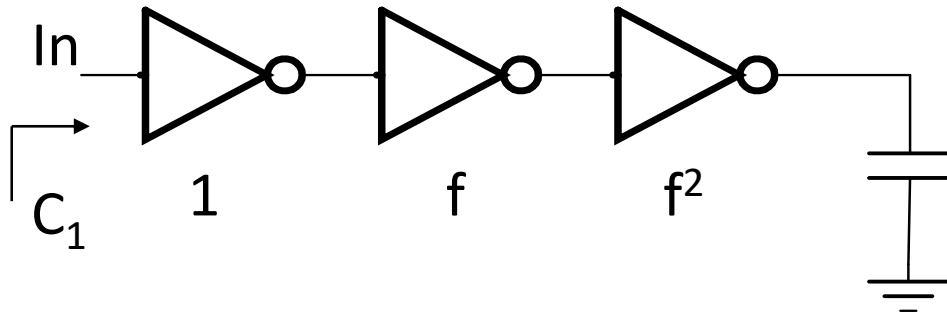


- The number of transistor required to implement an N fan-in is **2N** => area, capacitance
- Propagation delay deteriorates rapidly as a function of fan-in (# of inputs) – **Quadratically**



# 主要内容 (11)

- Digital power consumption:  $P_{\text{switching}} = \alpha C V_{DD}^2 f$
- Inverter: 反相器的阈值电压和  $(W/L)_{\text{pmos}} / (W/L)_{\text{nmos}}$  为成正比
- Delay: 反相器延时  $t_p = t_{p0} (1 + C_{\text{ext}} / \gamma C_g)$

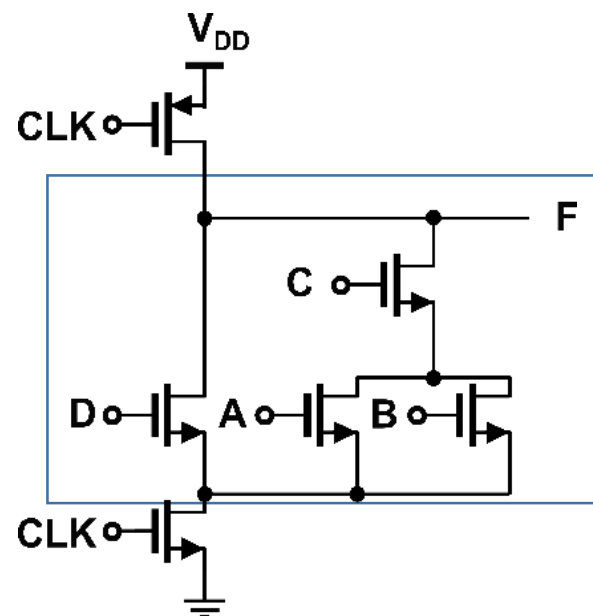
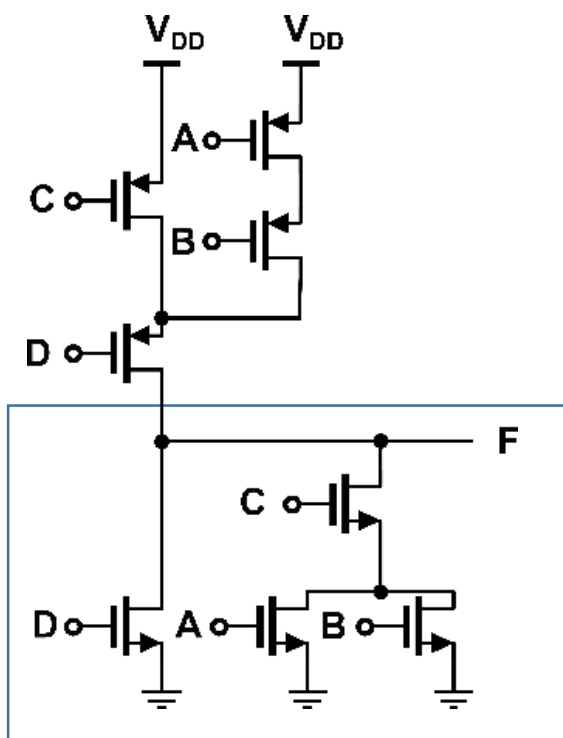


$$N = \ln(F)$$

$$f = 2.71828 = e$$

# 主要内容 (12)

- 传输门, 组合逻辑, 动态逻辑 (两者的定义与区别)
- 从逻辑表达式 到电路拓扑图 到版图

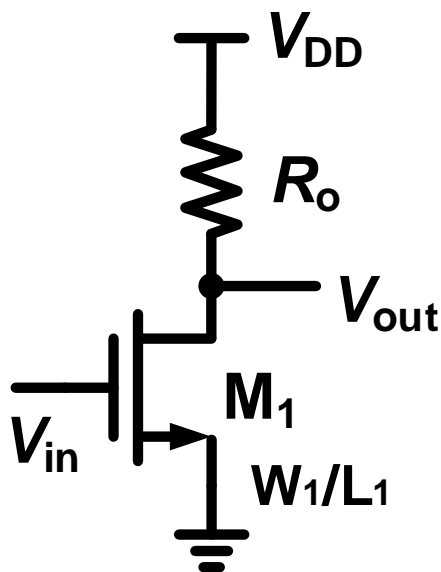




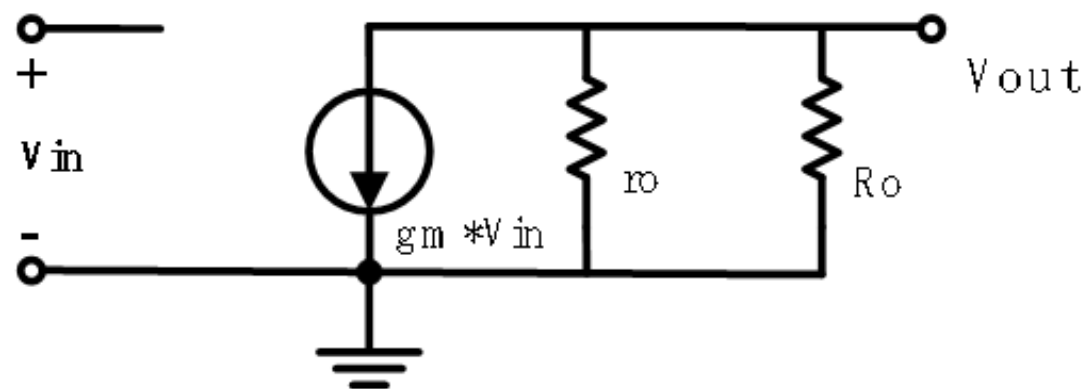
# Analog Example (1)

A single-stage amplifier is shown in Fig.4, assuming  $\gamma=0$ ,  $\lambda \neq 0$  and  $r_o \gg 1/g_m$ .

- (1) Please give its **equivalent small-signal circuits**. And calculate the symbolic small-signal **output resistance**,  $r_{out}$ , and **the voltage gain**,  $A_v$ ;
- (2) If the width  $W_1$  of  $M_1$  is increased, how does the gain change? Explain the reason;



(1)  $r_{out} = r_o // R_o$  (2分),  $A_v = g_m \times R_{out} = g_m \times (r_o // R_o)$  (2分)



(4分, 按实际绘图情况给分), 没有画  $r_o$  扣1分

(2)  $g_m = K \frac{W_1}{L_1} (V_{GS} - V_{TH})(1 + \lambda V_{DS})$ ,  $r_o = \frac{1}{\lambda I_D} = \frac{2}{\lambda K \frac{W_1}{L_1} (V_{GS} - V_{TH})^2 (1 + \lambda V_{DS})}$

$$A_v = g_m \frac{r_o R_o}{r_o + R_o} = K \left( \frac{W_1}{L_1} \right) (V_{GS} - V_{TH})(1 + \lambda V_{DS}) \frac{R_o}{1 + \lambda I_D R_o}$$

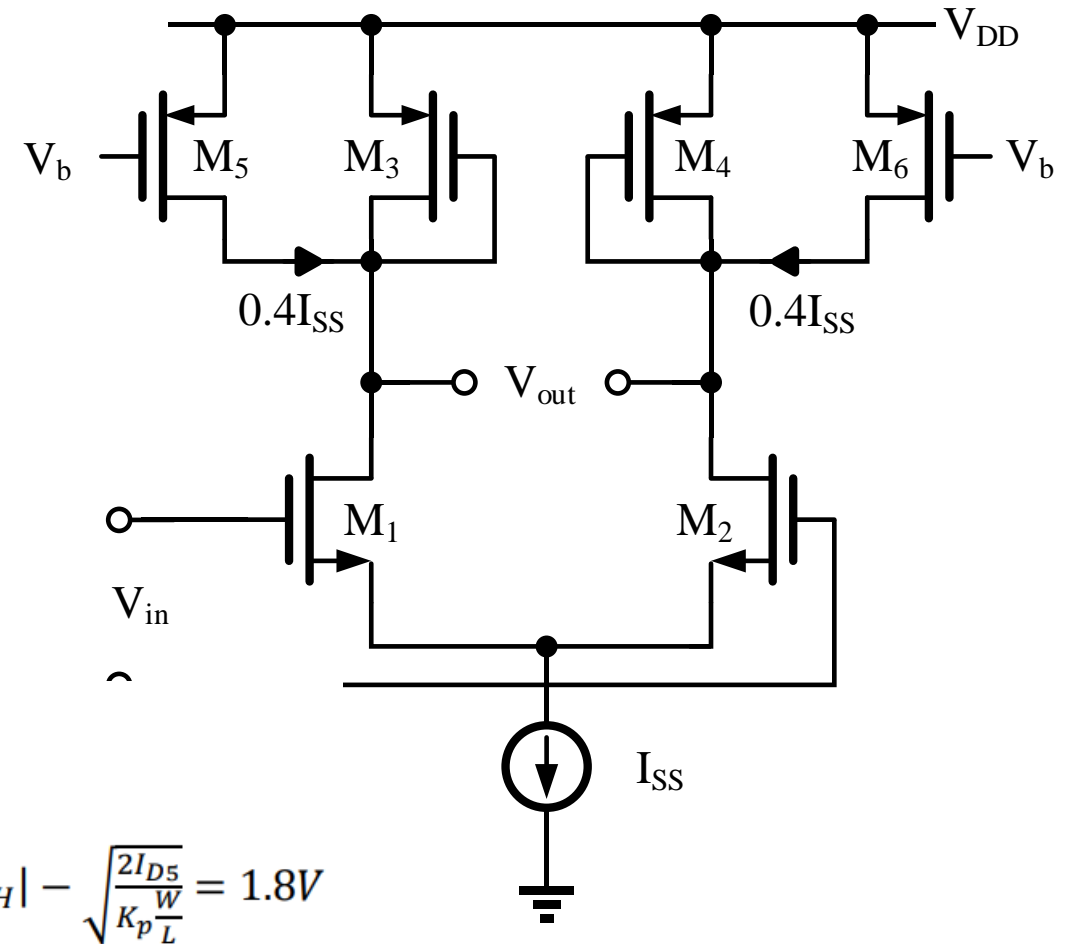
$$= K(V_{GS} - V_{TH}) \left( 1 + \lambda V_{DS} \right) R_o \left( \frac{1}{\frac{L_1}{W_1} + \frac{1}{2} \lambda K R_o (V_{GS} - V_{TH})^2 (1 + \lambda V_{DS})} \right)$$

所以总体的增益是增加的 (2分)

# Analog Example (2)

In the circuit of Fig 6.3, assume that  $I_{SS}=1\text{mA}$ ,  $V_{DD}=3\text{V}$  and  $W/L=50/0.5$  for all the transistors. And  $I_{D5}=I_{D6}=0.8 (I_{SS}/2)$ . Assuming  $\lambda \neq 0$ .

- Determine the **symbolic** voltage gain.
- Calculate  $V_b$ .
- What is the input common mode voltage range



$$\text{a) } A_V \approx -\frac{g_{m1}}{g_{m3}} = -\sqrt{\frac{K_n I_{D1}}{K_p I_{D3}}} = -\sqrt{\frac{134 \times 0.5 I_{SS}}{50 \times 0.2 \frac{I_{SS}}{2}}} = -3.66$$

$$\text{b) } I_{D5} = I_{D6} = 0.8 \frac{I_{SS}}{2} = 0.4\text{mA}, V_b = V_{DD} - V_{SG5} = V_{DD} - |V_{TH}| - \sqrt{\frac{2I_{D5}}{K_p \frac{W}{L}}} = 1.8\text{V}$$

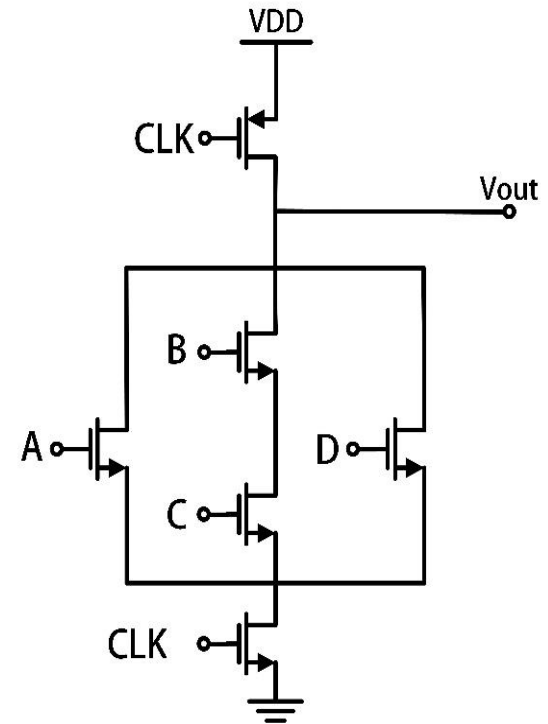
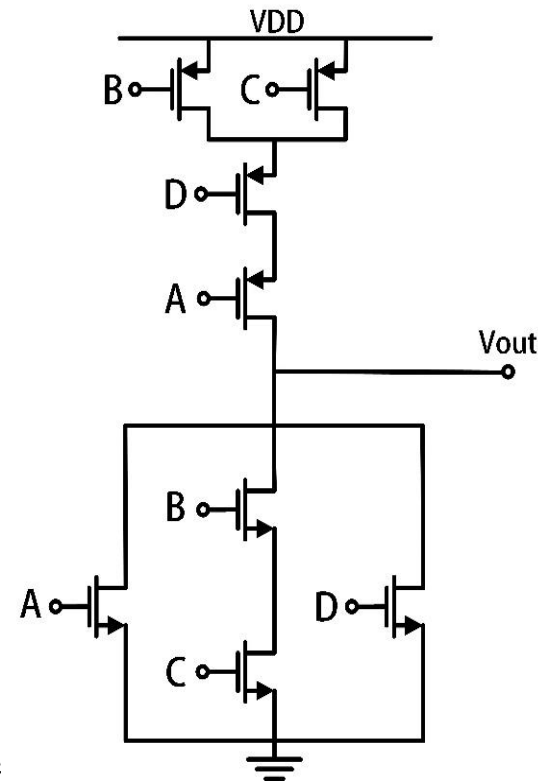
# Digital Example

(1) Please describe the concept of “**static logic circuit**” and “**dynamic logic circuit**” in digital circuits;

(2) Sketch 4-input gates  $F = \overline{A + BC + D}$  using the circuit techniques of **static CMOS** and **dynamic gates**, respectively.

The *static* circuits class, which each gate output is connected to either  $VDD$  or  $Vss$  via a low-resistance path at every point in time.

The *dynamic* circuit class, which relies on temporary storage of signal values on the capacitance of high-impedance circuit nodes.



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